



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC100N03MS G		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001823642					
<b>Package</b>				PG-TDSON-8-14		<b>Weight*</b>		118.56 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.709	0.60	0.60	5979	5979	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82		
	non noble metal	zinc	7440-66-6	0.039	0.03		328		
	non noble metal	iron	7439-89-6	0.778	0.66		6562		
wire	non noble metal	copper	7440-50-8	31.590	26.64	27.34	266448	273420	
	non noble metal	copper	7440-50-8	0.058	0.05	0.05	486	486	
	encapsulation	organic material	carbon black	1333-86-4	0.242	0.20		2038	
	plastics	epoxy resin	-	7.489	6.32		63170		
	inorganic material	silicondioxide	60676-86-0	40.588	34.25	40.77	342341	407549	
leadfinish	non noble metal	tin	7440-31-5	1.243	1.05	1.05	10481	10481	
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	316	316	
solder	non noble metal	tin	7440-31-5	0.021	0.02		176		
	noble metal	silver	7440-22-4	0.026	0.02		220		
	non noble metal	lead	7439-92-1	0.996	0.84	0.88	8403	8799	
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	zinc	7440-66-6	0.021	0.02		180		
	non noble metal	iron	7439-89-6	0.428	0.36		3606		
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.64	15.02	146423	150254	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
	non noble metal	iron	7439-89-6	0.017	0.01		143		
	non noble metal	copper	7440-50-8	16.898	14.25	14.26	142530	142716	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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